

# PRODUCT CHANGE NOTICE

**Assembly Site Qualification for Listed  
Intersil CABGA Packaged Products**

**Refer to:  
PCN03035**

**Date: August 21, 2003**

August 21, 2003

To: Our Valued Intersil Customers

Subject: **Assembly Site Qualification for Listed Intersil CABGA Packaged Products**

This notice is to inform you that Intersil is qualifying ChipPAC's Shanghai, China (CPS) facility as an alternate site for assembly of the *listed* CABGA (Chip Array Ball Grid Array) packaged products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The package and site-specific qualification activities are in process and expected to complete November 2003.

The ChipPAC Shanghai (CPS) facility is ISO 9002 certified and is currently an Intersil subcontractor qualified for assembly of other package families. The external package dimensions will remain the same. The CPS facility will utilize the Sumitomo G770LC mold compound and Ablestik 2000B die attach which provides for a more robust package. This material set has been qualified at ChipPAC's Ichon, Korea facility for use with lead free CABGA packages, which are mounted using higher reflow temperatures. The material set will change for the products listed in Attachment A. There will be no change in material set for the products listed in Attachment B. The material set is site specific and identified below:

**Assembly Site**

ChipPAC Shanghai, China  
ChipPAC Ichon, Korea  
ChipPAC Ichon, Korea (lead free products)  
Amkor Philippines

**Die Attach Material**

Ablestik 2000B  
Ablestik 8510AA  
Ablestik 2000B  
Ablestik 2000

**Mold Compound**

Sumitomo G770LC  
Sumitomo 7730  
Sumitomo G770LC  
Plaskon SMT-B1LV

The assembly qualification plans are designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. Details of the qualification activity are contained in Attachment C. The completed qualification results will be available by request. The remainder of the manufacturing operations (product electrical testing, shipment, etc.) will continue to be processed to established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system and by the assembly site code marked on the devices. The site code designator is branded on each device as an alpha character preceding the date code. The country of assembly site codes is as follows:

ChipPAC Shanghai, China (CPS) facility is "P"

ChipPAC Ichon, Korea (CPK) facility is "M"

Amkor Philippines (ATP) facility is “L”

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Intersil will take all necessary actions to conform to customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Upon completion of qualification, customers who have not previously negotiated change approval with Intersil may expect to receive product assembled at either the current or the newly qualified site.

If you have previously negotiated change approval with Intersil, please address this change immediately. To effectively facilitate product delivery, prompt review and approval is required.

If you have concerns with this change notice, Intersil must hear from you immediately. Please contact the nearest Intersil Sales Office or call the Intersil Corporate hot line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

## Jon Brewster

Jon Brewster  
Intersil Corporation

PCN03035

Cc: J.Seib T. Song B. Werner

## Attachment A – Affected Products

### *Material Set and Site Change*

HAA8P-51986R4781	ISL3874AIK-TKS2568	PRISM3K33-OEMKIT
HFA3845IK	ISL3877IK	PRISM3LAK18-OEMKIT
HFA3845IK96	ISL3877IK-TK	PRISM3LK18-HPPAKIT
HFA3845IK96S2463	ISL3880AIK	PRISM3LK18-NOPAKIT
HSP50216KI	ISL3880IK	PRISM3LK18-OEMKIT
HSP50217KI	ISL3880IK-T5	PRISM3LK33-HPPAKIT
HSP50415KI	ISL3886IK	PRISM3LK33-NOPAKIT
ISL3865AIK	ISL3886IK-T5	PRISM3LK33-OEMKIT
ISL3865AIK-TK	ISL3886PIK	PRISM3LP18-NOPAKIT
ISL3871AIK18	ISL3886PIK-T5	PRISM3LP18-OEMKIT
ISL3871AIK18-TK	ISL3890AIK	PRISM3P18-NOPAKIT
ISL3871AIK18H	ISL3890AIK-T5	PRISM3P18-OEMKIT
ISL3871AIK18H-TK	ISL3890IK	PRISM3P33-OEMKIT
ISL3871AIK33	ISL3890IK-T5	PRISM5-OEMKIT
ISL3871AIK33-TK	ISL3893IK	PRISMDB-OEMKIT
ISL3871IK18	ISL3893IK-T5	PRISMDBAPDK-OEMKIT
ISL3871IK18-TK	ISL5216KI	PRISMGT-OEMKIT
ISL3871IK18H	ISL5216KI-1	PRISMGT-A-NOPAKIT
ISL3871IK18H-TK	ISL5217KI	PRISMGT-A-OEMKIT
ISL3871IK33	ISL5239KI	PRISMGTAPDK-OEMKIT
ISL3871IK33-TK	ISL5416KI	PRISMGTB-OEMKIT
ISL3872IK18	PRISM25AP-OEMKIT	PRISMGTC-OEMKIT
ISL3872IK18-T5	PRISM25AP-PALESSKIT	PRISMGTGAPDK-OEMKIT
ISL3872IK33	PRISM25APX-OEMKIT	PRISMGTT-MACLESSKIT
ISL3872IK33-T5	PRISM25APX-PALESSKIT	PRISMGTT-NOPANOMAC
ISL3873BIK	PRISM25B-OEMKIT	PRISMGTUA-OEMKIT
ISL3873BIK-TK	PRISM25B-PALESSKIT	PRISMGTUA-T-OEMKIT
ISL3873BIK-TKS2568	PRISM25BX-OEMKIT	PRISMGTUC-NOPAKIT
ISL3873BIK-TKS2602	PRISM25BX-PALESSKIT	PRISMGTUC-OEMKIT
ISL3873BIK96S5001	PRISM3AK18-NOPAKIT	PRISMGTUCT-NOPAKIT
ISL3873CIK	PRISM3AK33-HPOEMKIT	PRISMGTUCT-OEMKIT
ISL3873CIK-TK	PRISM3AK33-NOPAKIT	PRISMGTUX-OEMKIT
ISL3873IKR5127	PRISM3AK33-OEMKIT	PRISMWWR-OEMKIT
ISL3874AIK	PRISM3K18-NOPAKIT	
ISL3874AIK-TK	PRISM3K18-OEMKIT	

## Attachment B – Affected Products

### *Site Change Only*

ISL3871AIK18Z	ISL3871IK18Z	ISL3872IK18Z
ISL3871AIK18Z-TK	ISL3871IK18Z-TK	ISL3872IK18Z-T5

## Attachment C – Qualification Plan

### ChipPAC Shanghai CABGA Qualification Plan

Stress/ Conditions	Duration	ISL3880IK18 256 I/O 17 x 17 CABGA  A2000B / G770 / AuPd wire Precondition L3	ISL3877IK 192 I/O 14 x 14 CABGA  A2000B / G770 / AuPd wire Precondition L2	ISL5216KI 196 I/O 12 x 12 CABGA  A2000B / G770 / AuPd wire Precondition L3
HAST, unbiased * 130C / 85% RH	96 hours	78	78	78
Storage Ta = 150C	168 hours 1k hours	78	78	78
Temp Cycle * -65C to +150C	200 cycles 500 cycles 1k cycles	78	78	78
MRT post electrical results	MRT #	L2 - 22 L3 - 22	L2 - 22 L3 - 22	L2 - 22 L3 - 22
Accelerated Bond Pull 200C, 96 hr.	Report # Average (g) Std Dev. (g) Minimum (g) Maximum (g) # Lifted Bonds	5	5	5
Accelerated Bond Pull 175C, 96 hr.	Average (g) Std Dev. (g) Minimum (g) Maximum (g) # Lifted Bonds	5	5	5

\* Preconditioned to level shown in header.